



IN THE ABSTRACT

Cancel abstract, and substitute therefore on a separate page the following

Abstract of the Disclosure:

-- ABSTRACT OF THE DISCLOSURE

A doped region is provided on a substrate. A plane with conductive useful structures and a conductive filler structure is arranged at the surface of the substrate. The conductive filler structure is conductively connected to the doped region. In this way, charging of the conductive filler structure, which is provided for improving the planarity of the circuit arrangement and has no circuit-oriented function, is avoided.--

REMARKS

The Office Action has been carefully reviewed, and the Examiner's comments are acknowledged and appreciated.

Concerning priority, Applicants respectfully submit that a certified copy of the German application establishing priority was filed on January 14, 2000, as indicated on the Notification of Acceptance of Application Form PCT/DO/EO/903, which was mailed on March 7, 2000.

A proper Declaration stating the Title of the Invention in English will be provided before the close of prosecution on the merits.

The Abstract of the Disclosure has been cancelled and replaced by an Abstract that recites the required correction. Hence, Applicants respectfully request withdrawal of this objection. A marked-up copy of the Abstract is provided reflecting the correction made.

On page 1 of the specification, the last paragraph has been cancelled and

replaced with a new paragraph that recites the required correction. Hence, Applicants respectfully request withdrawal of this objection. A marked-up copy of the paragraph is provided reflecting the correction made.

Concerning the 35 U.S.C. 112, second paragraph, rejection of the claims, the Examiner's attention is directed to the Preliminary Amendment filed along with this application, wherein claims 1 – 10 as filed have been canceled and replaced by new claims 11 – 21. The Preliminary Amendment also contains a request that the new claims be examined in favor of the claims as filed. Thus, Applicants respectfully submit that the new claims do indeed particularly and distinctly claim the subject matter of their invention, thereby making this rejection moot.

Concerning the 35 U.S.C. 102 rejection of claims 1- 10, Applicants respectfully submit that this rejection is moot in that these claims have been cancelled in favor of new claims 11 – 21.

Nevertheless, Applicants respectfully submit that Uehara, et al. fails to disclose or suggest the integrated circuit arrangement recited in claims 11 – 21. Thus, claims 11 – 21 are patentable over this reference.

The remaining prior art references cited in the Office Action have been reviewed, but no reference was noted to anticipate or render obvious any of Applicants' claims.

No new matter has been inserted in this application.

Therefore, Applicant submits that all objections and rejections have been successfully overcome or rendered moot and that this application is in proper condition for allowance, which action is earnestly solicited. However, if there are remaining issues to be addressed, Applicant respectfully requests that the examiner

contact the undersigned Attorney at once to discuss expedient resolution of such issues.

Respectfully submitted,

Steven H. Noll

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231, on October 15, 2001.

Steven H. Noll

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[-- ABSTRACT OF THE DISCLOSURE]

A doped region is provided {in} [on] a substrate. A plane with conductive useful structures and a conductive filler structure is arranged at the surface of the substrate. The conductive filler structure is conductively connected to the doped region. In this way, {a} charging of the conductive filler structure, which is provided for improving the planarity of the circuit arrangement and has no circuit-oriented function, is avoided. [- -]

{Figure 6}



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[-] When the useful structures and the filler structures are composed of conductive material, then a charging of the filler structures can occur during operation. In order to avoid this, the filler structures are applied to a fixed potential, as disclosed in Widmann[,] et al. {this} [This] contacting ensues via a specific wiring {that is} arranged in a metallization {[sic]} [plane] arranged above the useful and filler structures. This additional wiring and the contacts between the additional wiring and the filler structures {makes the} [make] production of the layout more difficult. [- -]

